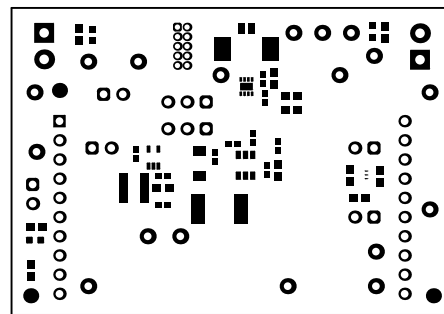
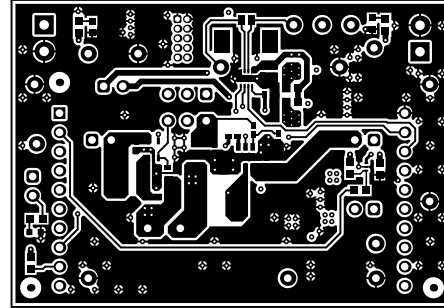


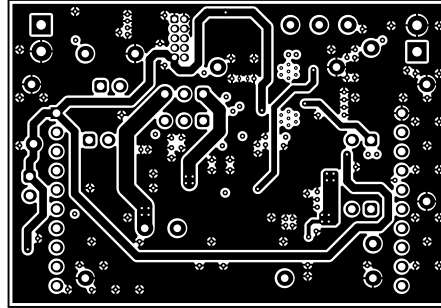
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01586 Board 2		
PLOT NAME = Top Overlay	GENERATED : 2/2/2018	1:04:49 PM	TEXAS INSTRUMENTS



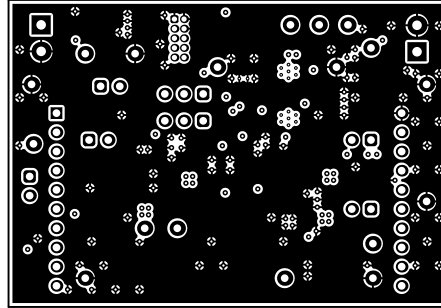
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01586 Board 2		
PLOT NAME = Top Solder Mask	GENERATED : 2/2/2018	1:04:50 PM	TEXAS INSTRUMENTS



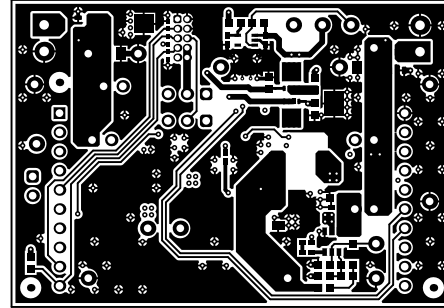
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: TIDA-01586 Board 2		
PLOT NAME = Top Layer	GENERATED : 2/2/2018	1:04:51 PM	TEXAS INSTRUMENTS



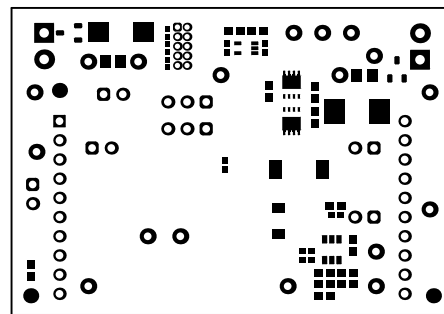
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 2 - PWR	TID #: TIDA-01586 Board 2		
PLOT NAME = Signal Layer 1	GENERATED : 2/2/2018	1:04:52 PM	TEXAS INSTRUMENTS



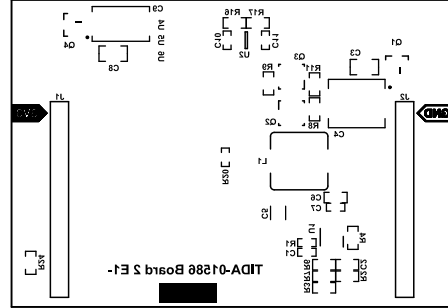
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 3 - GND	TID #: TIDA-01586 Board 2		
PLOT NAME = Signal Layer 2	GENERATED : 2/2/2018	1:04:53 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - Bottom Layer	TID #: TIDA-01586 Board 2		
PLOT NAME = Bottom Layer	GENERATED : 2/2/2018	1:04:53 PM	TEXAS INSTRUMENTS

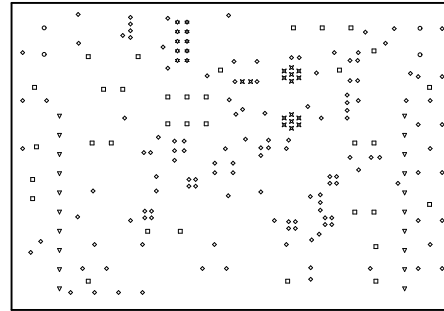


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01586 Board 2		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/2/2018	1:04:54 PM	TEXAS INSTRUMENTS



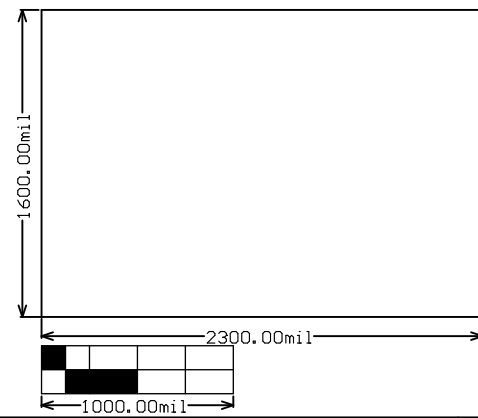
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01586 Board 2		
PLOT NAME = Bottom Overlay	GENERATED : 2/2/2018	1:04:55 PM	TEXAS INSTRUMENTS





Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊠	16	7.87mil (0.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
◇	136	12.00mil (0.305mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊛	10	27.56mil (0.700mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
□	34	40.00mil (1.016mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
▽	20	40.16mil (1.020mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
○	4	50.00mil (1.270mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
	220 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01586 Board 2		
PLOT NAME = Drill Drawing	GENERATED : 2/2/2018	1:04:56 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01586 Board 2		
PLOT NAME = Board Dimensions	GENERATED : 2/2/2018	1:04:57 PM	TEXAS INSTRUMENTS

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